

SOT784-1

plastic low profile quad flat package; 100 leads; body 14 x 20 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP100
Package type industry code	LQFP100
Package style descriptive code	LQFP (low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	136E27
JEDEC package outline code	MS-026
JEITA package outline code	ED-7311PD
Mounting method type	S (surface mount)
Issue date	14-8-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	19.9	-	20	20.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	1.6	1.6	mm
A ₂	package height	1.35	-	1.4	1.45	mm
n ₂	actual quantity of termination	-	-	100	-	

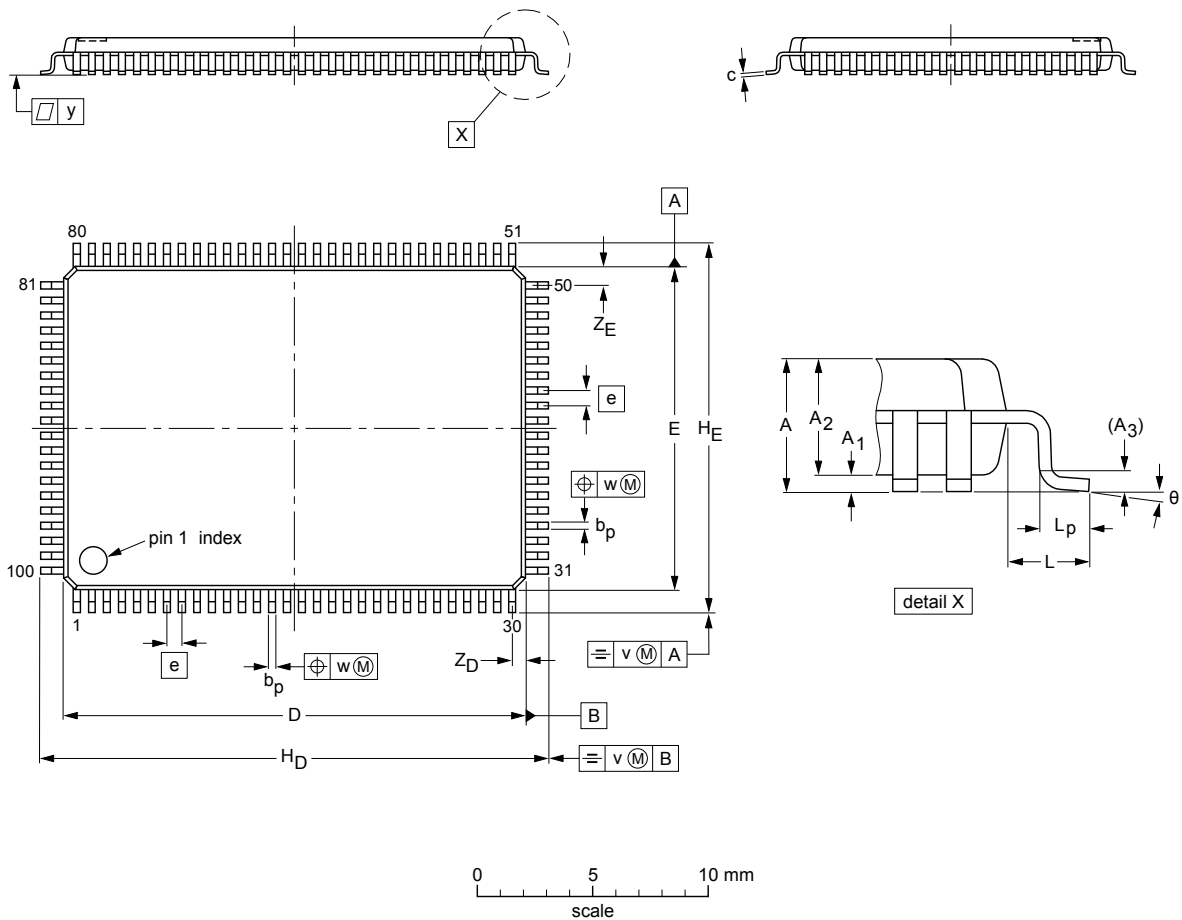


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2. Package outline

LQFP100: plastic low profile quad flat package; 100 leads; body 14 x 20 x 1.4 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	1.6	0.15 0.05	1.45 1.35	0.25	0.38 0.22	0.20 0.09	20.1 19.9	14.1 13.9	0.65	22.25 21.75	16.25 15.75	1	0.75 0.45	0.2	0.13	0.1	0.8 0.4	1.0 0.6	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT784-1	136E27	MS-026	ED-7311PD			02-08-14

Fig. 1. Package outline LQFP100 (SOT784-1)

3. Soldering

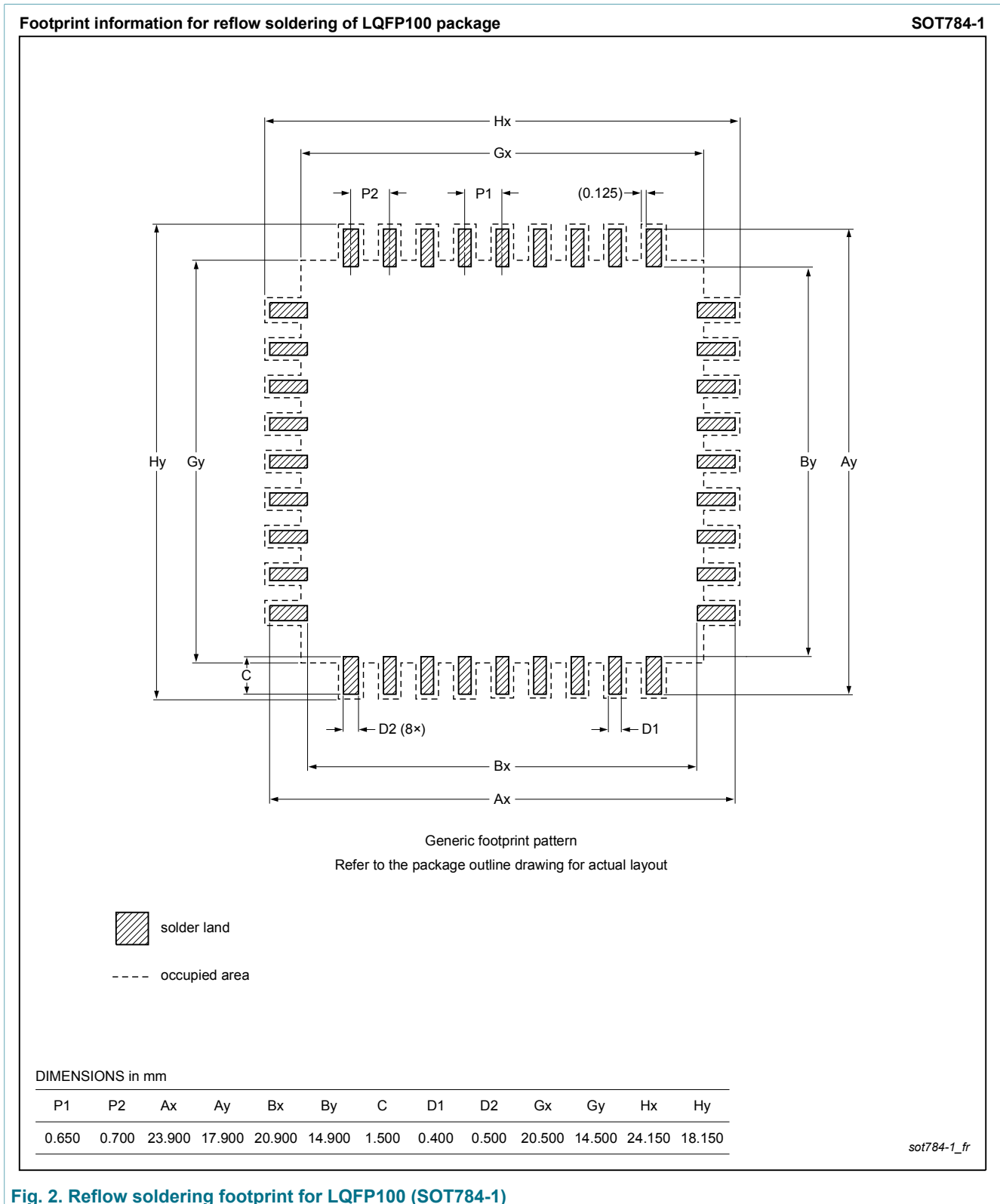


Fig. 2. Reflow soldering footprint for LQFP100 (SOT784-1)

4. Legal information

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For sales office addresses, please send an email to: salesaddresses@nxp.com

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